

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph from page 6, line 18 to page 7, line 2 with the following amended paragraph:

The integrated circuit elements are preferably disposed in a multi-layer ceramic material, such as LTTC ceramics (= low temperature cofired ceramics). LTTC material allows for a high integration density of network elements. Alternatively, a multi-layer substrate can comprise layers of HTCC (= high temperature cofired ceramics), ~~silicene~~ silicon and other semiconductors (e.g., GaAs, SiGe, ~~silicene~~ silicon oxide, other oxides) or organic materials (e.g., laminates, plastic).

Please replace the paragraph on page 10, lines 5 and 6 with the following amended paragraph:

The multi-layer substrate can contain, for example, layers of ceramic, ~~silicene~~ silicon, oxides (e.g., ~~silicene~~ silicon dioxide) or organic materials.